



# BW16 Datasheet

Version V1.0  
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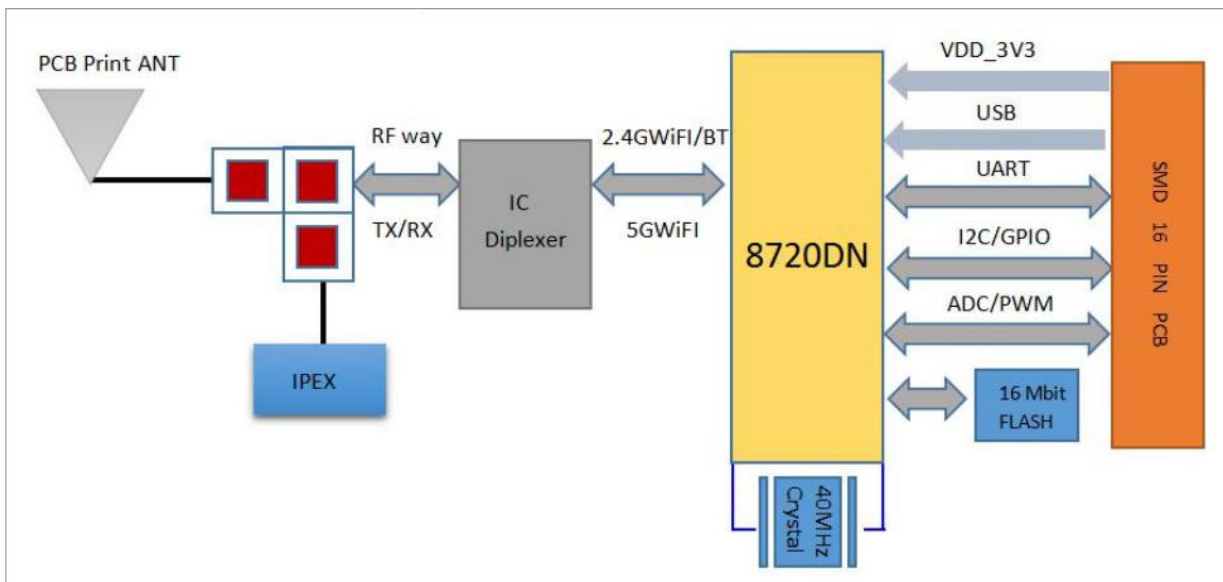
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## I . Product overview

BW16 is a dual-frequency Wi-Fi Bluetooth SoC module based on RTL8720DN. BW16 supports dual-frequency (2.4ghz or 5ghz) WLAN and low-power Bluetooth 5.0; it integrates ARM V8 (compatible with Cortex-M4F) high-performance MCU, ARM V8M (compatible with Cortex-M0) low-power MCU, WLAN (802.11 a / b / g / n), MAC, Bluetooth baseband and RF baseband) and provides a set of configurable GPIO ports for the control of different peripherals.

BW16 integrates internal memory, supports some simple application development, and realizes complete Wi-Fi and BT 5.0 protocol functions.



## Features

- Support 802.11a/b/g/n 1x1, 2.4GHz or 5GHz.
- Support HT20/HT40 mode.
- Support for low power beacon listening mode, low power reception mode and low power pending mode.
- Embedded AES / DES / SHA hardware engine.
- Support TrustZone-M and safed start up.

- Support SWD debug port access protection and prohibition mode.
- Support BLE and BT5.0
- Bluetooth supports high power mode (7dBm, share the same PA with WiFi)
- Wi-Fi and BT share the same antenna.
- Support STA/AP/STA+AP operating mode
- Support the Smart Config (APP) /AirKiss(wechat) of Android、IOS (One-click distribution network)
- Support serial port local upgrade and remote firmware upgrade (FOTA)

## Parameters

Figure 1 Main Parameter

Model	BW16
Package	SMD-16
Size	24*16*3(±0.2)MM
Antenna	PCB or IPEX antenna
Frequency range	2400-2483.5MHz or 5180-5825MHz
Bluetooth	BT5.0
Bluetooth frequency range	2.402GHz - 2.480GHz
Operating temperature	-20 °C ~ 70 °C
Storage Environment	-40 °C ~ 125 °C , < 90%RH
Power supply	Voltage 3.0V ~ 3.6V, Typ:3.3V, current >450mA
Interface	UART/GPIO/ADC/PWM/IIC/SPI/SWD
Certification	RoHS、FCC、CE、SRRC

## II. Electrical parameter

### Noted:

BW16 module is an electrostatic sensitive device, which needs special ESD precautions. When used ESD protective devices should be added. The correct ESD processing and packaging must be adopted in the transportation, operation and use of BW16 modules. Do not touch the module by hand or weld with a non-antistatic soldering iron to avoid damage to the module.

Parameter	Min	Typ	Max	Unit
DC 3.3V (with internal regulator and integration CMOS PA)	3.0	3.3	3.6	V
Figure I/O supply voltage	1.76	1.8-3.3	3.3	mA
DC_I0_33 (3.3V I / O rated current)			50	mA
Electrostatic protection (VESD)			2000	V

## Radio Performance

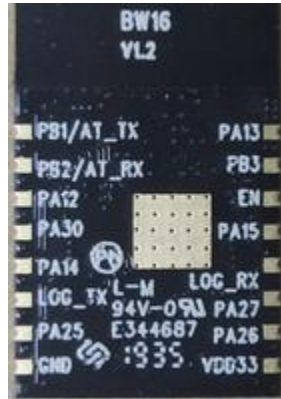
Description	Typ	Unit
Operating frequency	2400-2483.5 or 5180-5825	MHz
<b>Output Power</b>		
11a mode, PA output power	14±2	dBm
11n mode, PA output power	14±2	dBm
11g mode, PA output power	15±2	dBm
11b mode, PA output power	16±2	dBm
Bluetooth output power	7±2	dBm
<b>Sensitivity</b>		
CCK, 1 Mbps	≤ -90	dBm
CCK, 11 Mbps	≤ -85	dBm
6 Mbps (1/2 BPSK)	≤ -88	dBm





## IV. Pin definition

BW16 has 16 interface, refer to following Pin diagram, table 2.2 is definition of interfaces.



BW16 Pin diagram

Table 2.2 Pin function definition

No.	Name	Function
1	PA13	LP_PWM1/SPI1_MISO
2	PB3	ADC/SWD_CLK
3	CHIP_EN	Chip enable port
4	PA15	SPI1_CS
5	PA8	UART_LOG_RXD
6	PA27	SWD_DATA
7	PA26	LP_I2C_SDA/LP_PWM5
8	VDD_3V3	3.3V (VDD) ; Max: 450mA
9	GND	Ground
10	PA25	LP_I2C_SCL/LP_PWM4
11	PA7	UART_LOG_TXD
12	PA14	SPI1_CLK
13	PA30	LP_PWM1
14	PA12	SPI1_MOSI/LP_PWM0
15	PB2	LP_UART_RXD
16	PB1	LP_UART_TXD

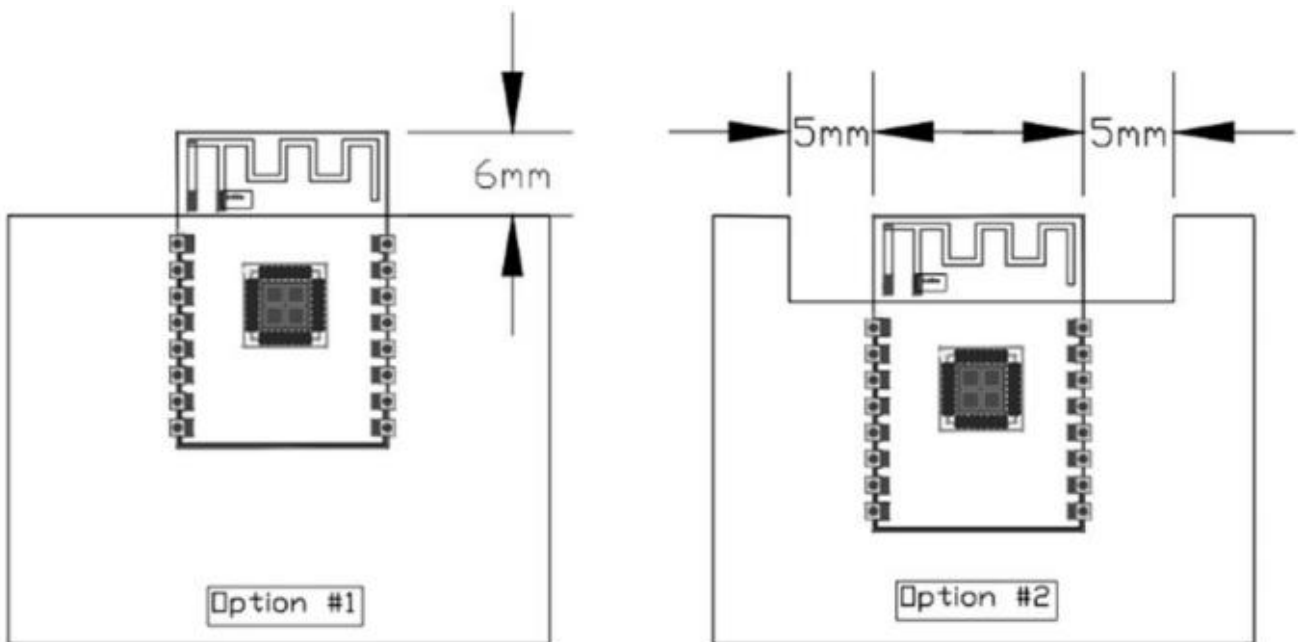


## 2、Antenna layout requirements

(1)、Installation position on the main board, advise for following two ways:  
Option 1: The module is placed on the edge of the main board, and the antenna area is extended out of the edge of the main board.

Option 2: Put the module on the edge of the motherboard, and the edge of the motherboard is hollowed out in the antenna position.

(2)、In order to meet the performance of the on-board antenna, metal parts are prohibited from being placed around the antenna.



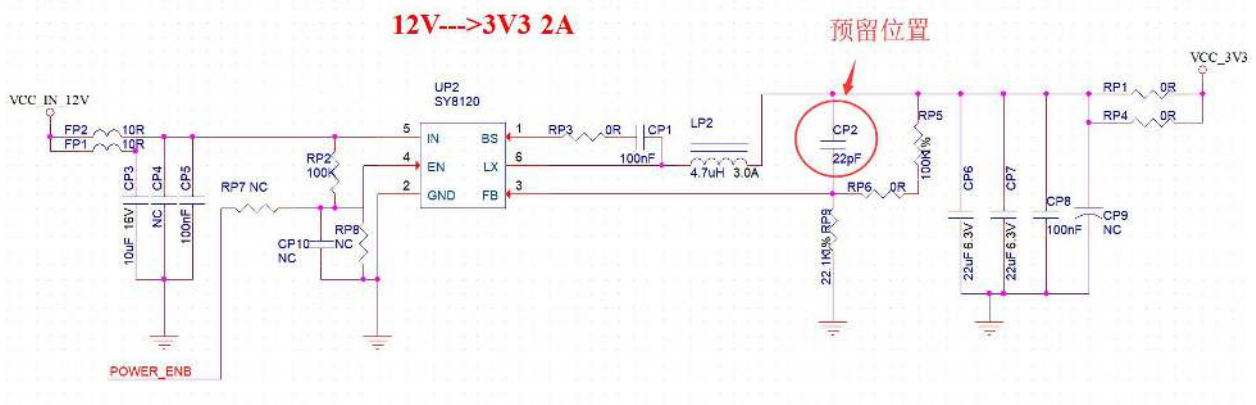
## 3、Power Supply

(1)、Recommended voltage 5V, Peak:Current over 500mA .

(2)、It is recommended to use the LDO power supply; If DC-DC is used, the ripple is controlled within 30 mV.

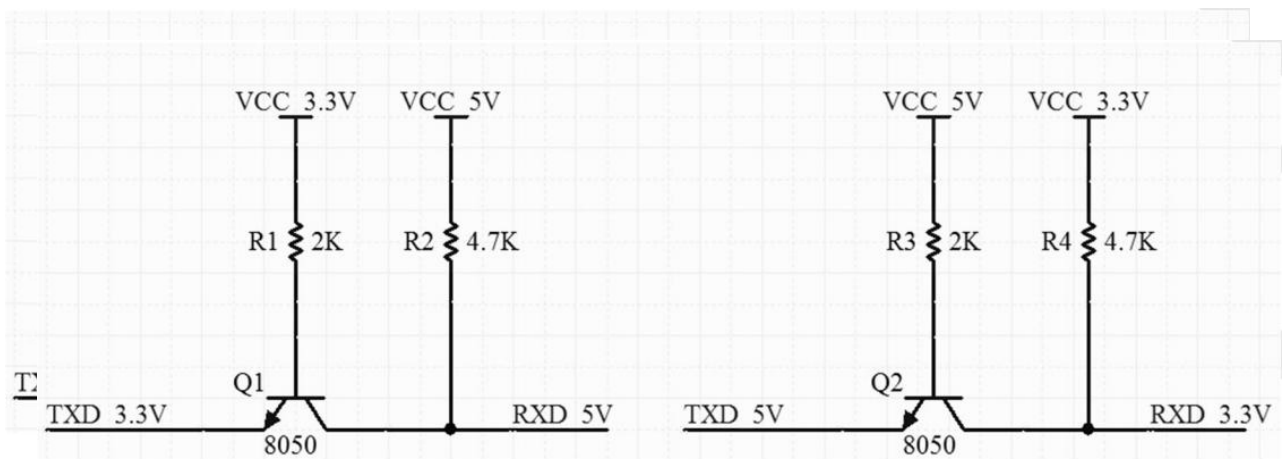
(3)、DC-DC power supply circuit is recommended to reserve the position of the dynamic response capacitor, and the output ripple can be optimized when the load change is large.

(4)、Proposed addition of ESD Devices to 5V Power supply Interface.



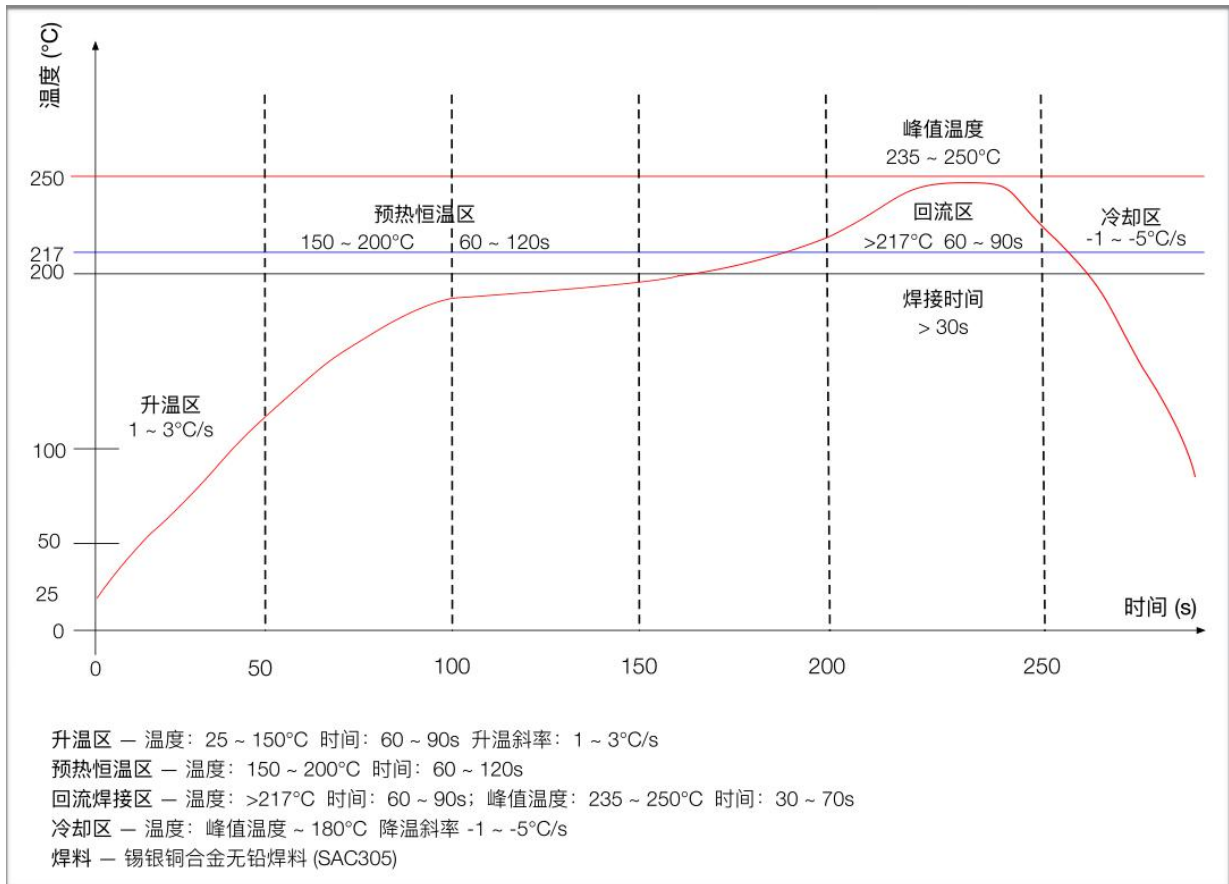
#### 4、GPIO

- (1) At the periphery of the module, some GPIO ports are led out, and a resistance of 10-100 ohms can be connected in series on the IO port for use. This suppresses overshoot and is more stable on both sides. Help for both EMI and ESD.
- (2) For the up-and-down drawing of the special io-port, reference will be made to the use description of the specification, which will affect the start-up configuration of the module.
- (3) The IO port of the module is 3.3 v. If the main control does not match the io-level of the module, it is necessary to increase the level conversion circuit.
- (4) If the IO interface is directly connected to the peripheral interface, or the pins and other terminals, it is recommended to reserve the ESD device near the terminal at the IO trace.



Level switching circuit

## VII. ROLLING OF Reflow soldering



## VIII. Package Information

As shown below, the packing of BW16 is a tape.



## IX. Contacts

Company website: <https://www.ai-thinker.com>

Developer Wiki: <http://wiki.ai-thinker.com>

Company forum: <http://bbs.ai-thinker.com>

Sampling purchasing: <https://anxinke.taobao.com>

Business cooperation: [sales@aithinker.com](mailto:sales@aithinker.com)

Technology support: [support@aithinker.com](mailto:support@aithinker.com)

Company address: Room410, Building C, Huafeng Intelligence Innovation Port,

Gushu, Xixiang, Baoan District, Shenzhen China 518126

